



<https://ewh.ieee.org/conf/edtm/2021>

5th IEEE Electron Devices Technology and Manufacturing (EDTM) Conference, 2021

EDTM2021 Theme: **Intelligent Technologies for Smart and Connected Life**

Chengdu, China

March 9th–12th, 2021

New Dates: April 8-11, 2021 (Hybrid)

EDTM2021 will go **HYBRID** comprising a normal **in-Person/on-Site meeting** with large attendance and a **Virtual Component** (presentation, participation and exhibition) for those with travel restriction due to COVID-19.

The **IEEE Electron Devices Technology and Manufacturing (EDTM) Conference 2021** is a four-day meeting to be held in Chengdu, China, during **April 8th to 11th, 2021**. Sponsored by IEEE *Electron Devices Society* (EDS), **EDTM** is a premier conference, providing a unique forum for discussions on a broad range of device/manufacturing-related topics. **EDTM** rotates among the hot-hubs of semiconductor manufacturing in Asia, coming to China in 2021.

Whether you are seeking to enhance brand recognition, reinforce your reputation as an industry leader, or demonstrate your products, an **EDTM 2021** exhibitor will have the opportunity to achieve your goals by showcasing products or services to the attending researchers and engineers from the industry, academia and R&D institutes worldwide. **EDTM 2021 invites you to become an exhibitor in this highly attended conference!** **EDTM 2021** will be held in Chengdu, China, during April 8-11, 2021. For more information, please visit: <https://ewh.ieee.org/conf/edtm/2021>.

Exhibition Locations & Time:

- At **EDTM 2021** conference site
- April 9 – 10, 2021

Exhibition Costs:

- **US\$3K** for a Standard Booth (3m X 3m)
- Multiple-Booths are available at pro-rated costs

Exhibition Benefits:

- Each exhibitor will give a 3-min presentation at the **Business & Exhibition Night** on 4/10 (jointly with Poster II Sessions and Exhibition)
- Exhibitor's websites will appear at the **EDTM 2021** exhibitor web page
- Exhibition will be held jointly with the popular Interactive/Poster Sessions

EDTM2021 will go **HYBRID** comprising:

- **Normal in-Person/on-Site meeting featuring on-site Exhibition**, and
- **Virtual Components, including Virtual Exhibition Booths**

Contact:

Sponsorships & Exhibition co-Chairs:

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